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## Low k Dielectric Materials

Guest Editor:

### Prof. Dr. Rajendra Singh

The Holcombe Department of  
Electrical and Computer  
Engineering, Clemson University,  
105 Riggs Hall, Room 206,  
Clemson, SC 29634, USA

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submissions:

**closed (30 June 2012)**

### Message from the Guest Editor

Dear Colleagues,

For Low k dielectric materials, the value of dielectric constant is less than the dielectric constant of silicon dioxide. Such materials are of great importance for multi-level interconnections of nanoelectronics and radio frequency (RF) devices and circuits. Other applications include optoelectronics, 3-D integrated circuits, microelectromechanical systems (MEMS), nanoelectromechanical (NEMS), sensors and detectors and packaging of various types of devices and circuits. All topics related to synthesis, and properties of low-k dielectrics, various processing techniques, process integration, performance and reliability of low-K based devices, circuits and systems are of interest for this journal issue.

Dr. Rajendra Singh  
*Guest Editor*



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### Prof. Dr. Maryam Tabrizian

1. Department of Biomedical Engineering, Faculty of Medicine and Health Sciences, McGill University, Montreal, QC H3A 2B6, Canada

2. Faculty of Dentistry and Oral Health Sciences, McGill University, 3640 Rue University, Montreal, QC H3A 0C7, Canada

## Message from the Editor-in-Chief

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*Materials* Editorial Office  
MDPI, Grosspeteranlage 5  
4052 Basel, Switzerland

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